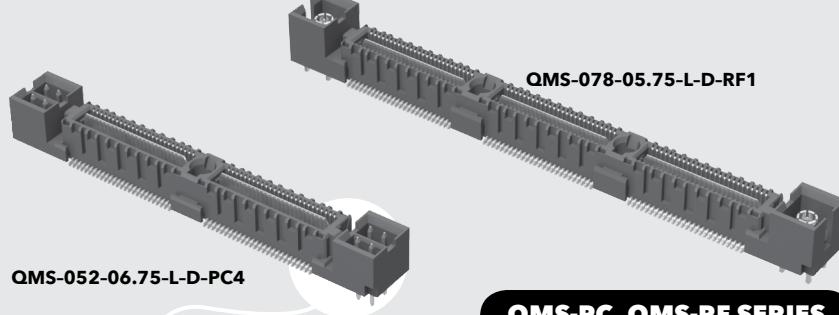




(0.635 mm) .025"



# HIGH-SPEED COMBO RF & POWER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?QMS](http://www.samtec.com?QMS)

### Insulator Material:

Liquid Crystal Polymer

### Terminal & Ground Plane Material:

Phosphor Bronze

### Plating:

Au over 50  $\mu$ " (1.27  $\mu$ m) Ni (Tin on Ground Plane Tail)

### Current Rating:

Signal Contact:

2.6 A per pin

(2 pins powered)

Power Contact:

4.0 A per pin

(4 pins powered per end)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

### Voltage Rating:

300 VAC/424 VDC

mated with QFS

### Operating Temp:

-55  $^{\circ}$ C to +125  $^{\circ}$ C

### RoHS Compliant:

Yes

## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (026-078)

### Board Stacking:

For applications requiring more than two connectors per board, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE

Contact Samtec

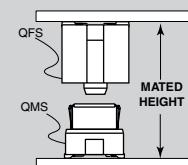
- Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) 0.62" thick board
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- Hot Pluggable

### Note:

Some lengths, styles and options are non-standard, non-returnable.

**Board Mates:**  
QFS-PC, QFS-RA-PC,  
QFS-RF

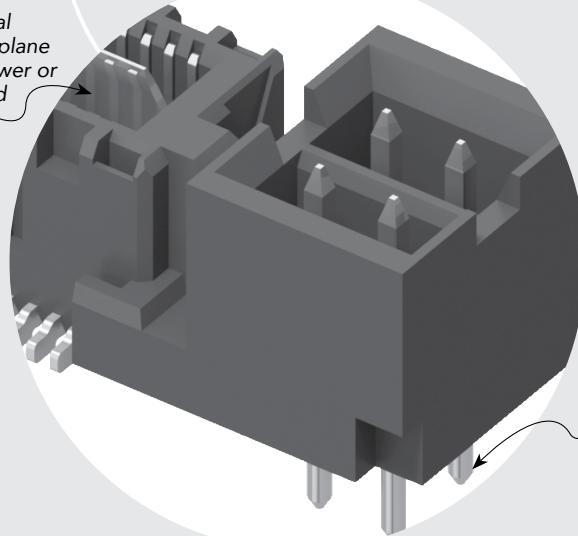
## APPLICATION



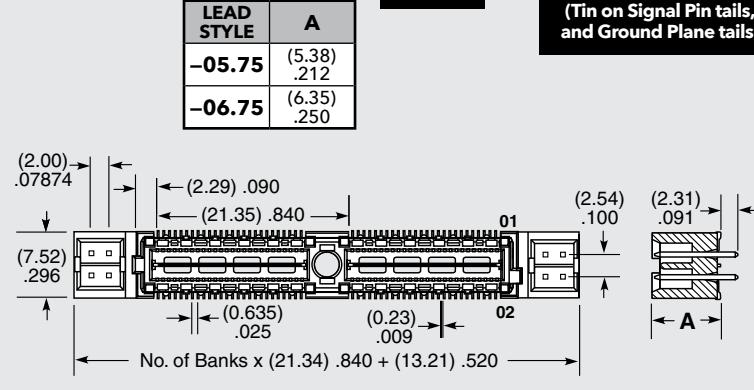
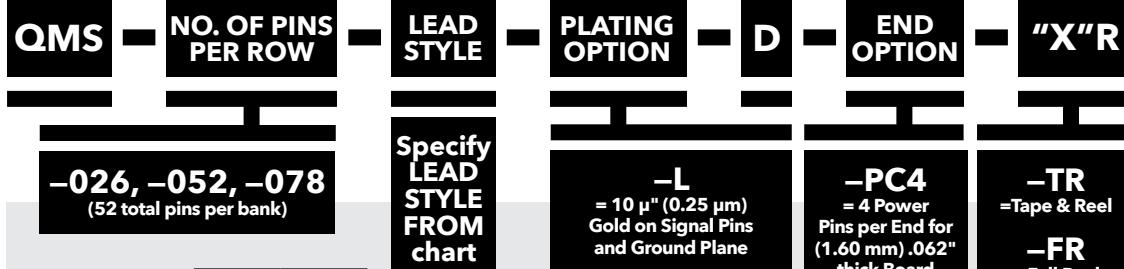
QMS	MATED HEIGHT*
-05.75	(10.00) .394
-06.75	(11.00) .433

\*Processing conditions will affect mated height. See SO Series for board space tolerances.

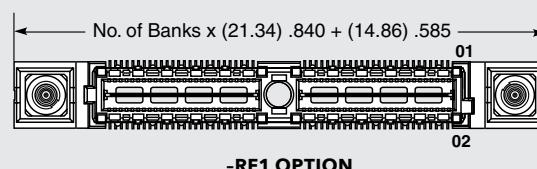
Integral metal plane for power or ground



Choice of Power and RF options

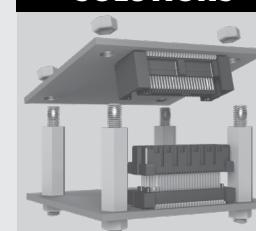


-PC4 OPTION



-RF1 OPTION

## OTHER SOLUTIONS



See SO Series for precision machined standoffs.